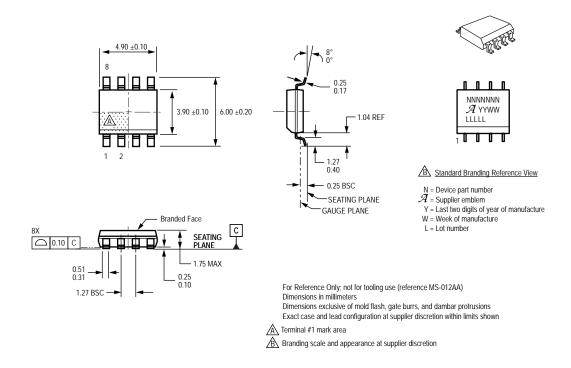
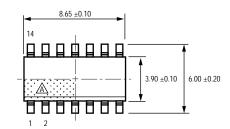


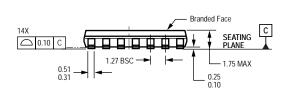
Designator: L
Type: 8-pin, narrow SOIC

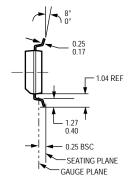


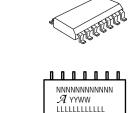


Designator: L Type: 14-pin, narrow SOIC









B Standard Branding Reference View

N = Device part number  $\mathcal{A}$  = Supplier emblem

 $\mathcal{A}$  = Supplier emblem
Y = Last two digits of year of manufacture

W = Week of manufacture

L = Lot number

For Reference Only; not for tooling use (reference MS-012AB)

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions Exact case and lead configuration at supplier discretion within limits shown

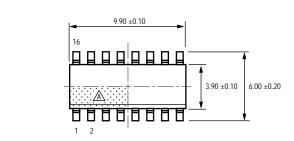
A Terminal #1 mark area

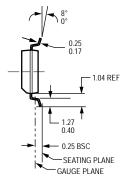
Branding scale and appearance at supplier discretion

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Type: 16-pin, narrow SOIC









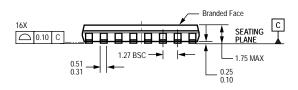
Standard Branding Reference View

N = Device part number  $\mathcal{A}$  = Supplier emblem

Y = Last two digits of year of manufacture

W = Week of manufacture

L = Lot number



For Reference Only; not for tooling use (reference MS-012AC)

Dimensions in millimeters

 $\label{eq:definition} \mbox{Dimensions exclusive of mold flash, gate burrs, and dambar protrusions}$ Exact case and lead configuration at supplier discretion within limits shown

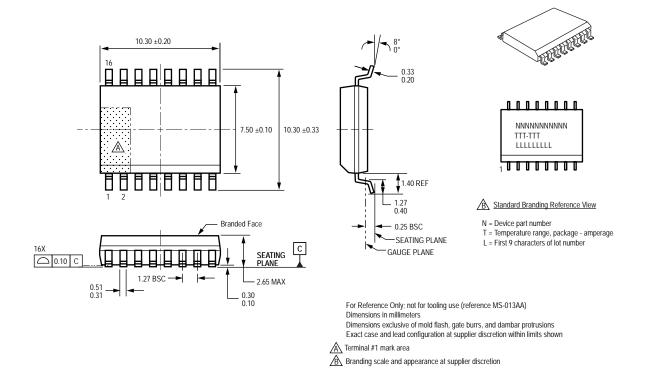
A Terminal #1 mark area

Branding scale and appearance at supplier discretion

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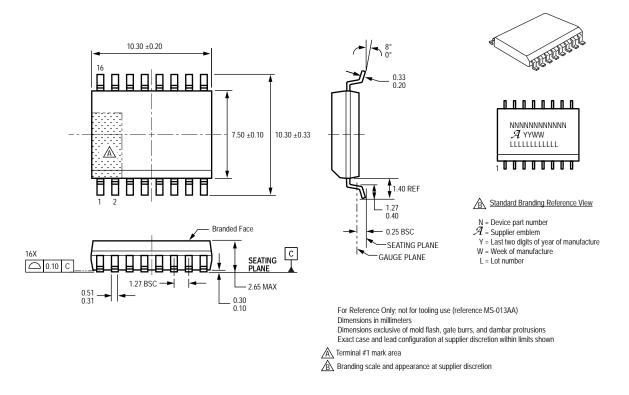
## Designator: LA

#### Type: Wide SOIC with internally fused pins for current sensing path





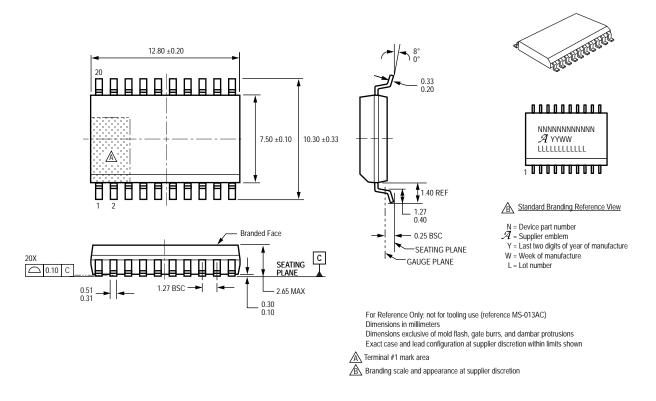
#### Type: 16-pin, wide SOIC with internally fused pins for thermal dissipation



Internal configuration of fused pins is device-dependent



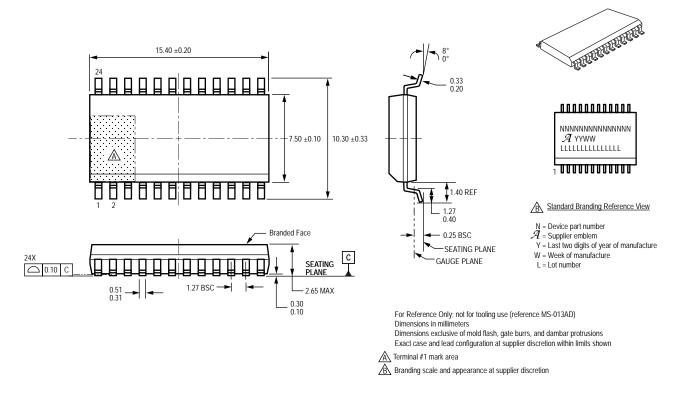
Type: 20-pin, wide SOIC with internally fused pins for thermal dissipation



Internal configuration of fused pins is device-dependent



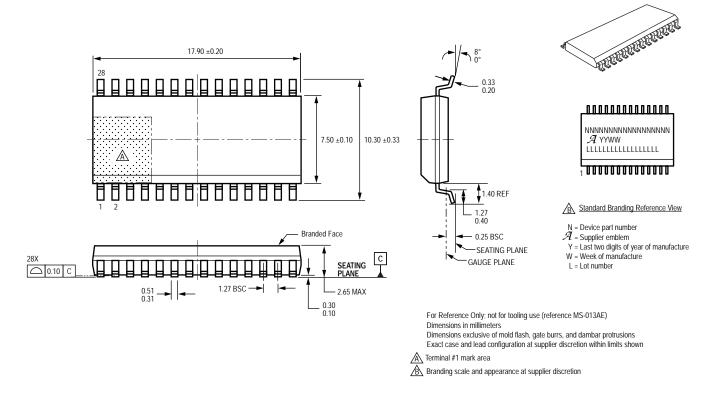
#### Type: 24-pin, wide SOIC with internally fused pins for thermal dissipation



Internal configuration of fused pins is device-dependent



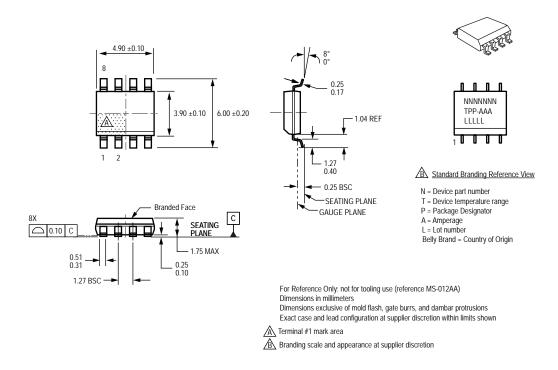
#### Type: 28-pin, wide SOIC with internally fused pins for thermal dissipation



Internal configuration of fused pins is device-dependent

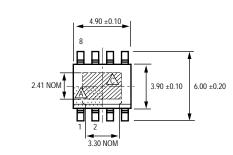
# Designator: LC

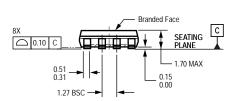
Type: Narrow SOIC with internally fused pins for current sensing path

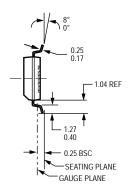


Designator: LJ

Type: Narrow SOIC with exposed thermal pad











B Standard Branding Reference View

N = Device part number  $\mathcal{A}$  = Supplier emblem

 $\mathcal{A}$  = Supplier emblem Y = Last two digits of year of manufacture

W = Week of manufacture

L = Lot number

For Reference Only; not for tooling use (reference MS-012BA)

Dimensions exclusive of mold flash, gate burrs, and dambar protrusions Exact case and lead configuration at supplier discretion within limits shown

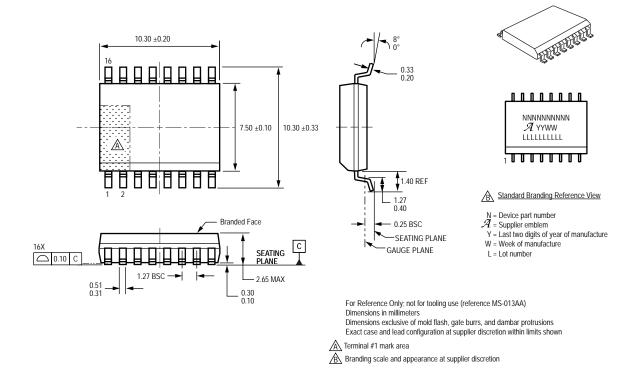
A Terminal #1 mark area

Branding scale and appearance at supplier discretion

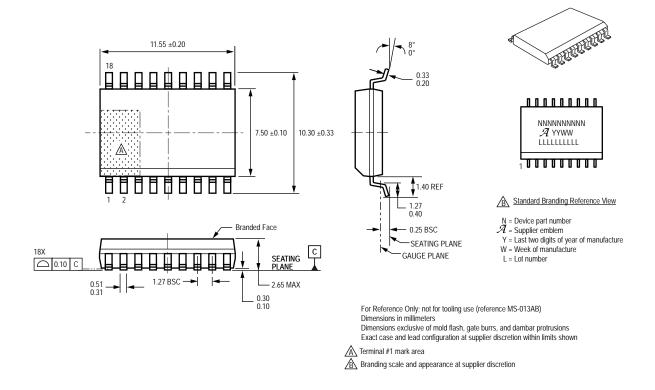
Exposed thermal pad (bottom surface); dimensions may vary with device

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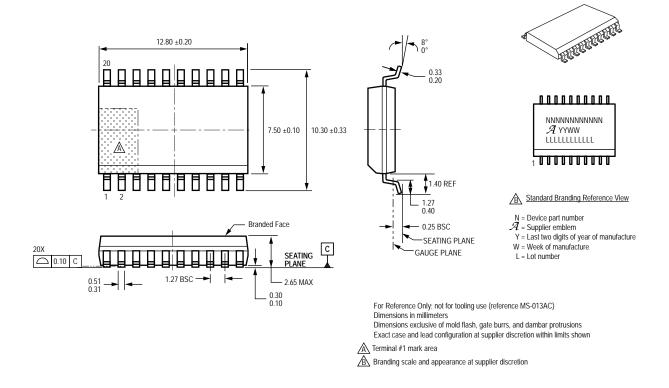
**Designator: LW**Type: 16-pin, wide SOIC



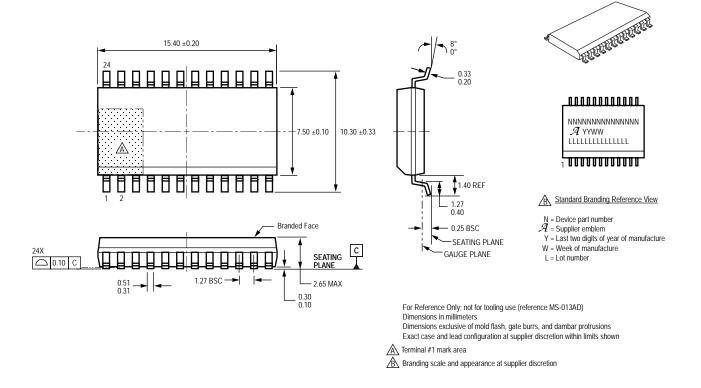
**Designator: LW**Type: 18-pin, wide SOIC



**Designator: LW**Type: 20-pin, wide SOIC



**Designator: LW**Type: 24-pin, wide SOIC



**Designator: LW**Type: 28-pin, wide SOIC

